

## Class AB Stereo Headphone Driver

### Features

- Operating Voltage
  - Single Supply 3V to 6V
  - Dual Supply  $\pm 1.5V$  to  $\pm 3.0V$
- High Signal-to-Noise Ratio 100dB
- Low Distortion -65dB
- Large Output Voltage Swing
- Excellent Power Supply Ripple Rejection
- Low Power Consumption
- Short-circuit Elimination
- Wide Temperature Range
- No Switch ON/OFF Clicks
- Available in 8 pin SOP ,DIP or TSSOP Package

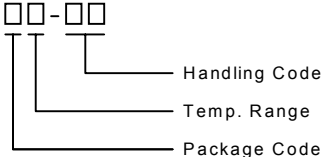
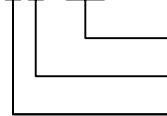

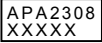
### Applications

- Portable Digital Audio

### General Description

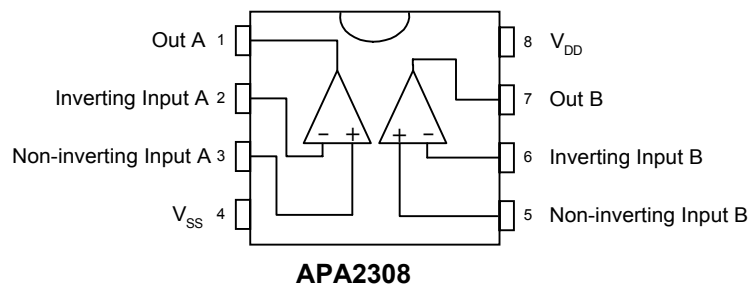
The APA2308 is an integrated class AB stereo headphone driver contained in an SO-8, a DIP-8 or a TSSOP-8 plastic package. The APA2308 is capable of delivering 280mW of max. Output power to an 8 $\Omega$  load or 110mW to a 32 $\Omega$  load with less than 10% (THD+N) from a 5V power supply. The device is fabricated in a CMOS process and has been primarily developed for portable digital audio applications .

### Ordering and Marking Information

APA2308 	Package Code J : PDIP - 8      K : SOP - 8 O : TSSOP - 8 Temp. Range I : - 40 to 85° C Handling Code TU : Tube      TR : Tape & Reel
APA2308 J : 	XXXXX - Date Code
APA2308 K : 	XXXXX - Date Code
APA2308 O : 	XXXXX - Date Code

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

## Block Diagram



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
$V_{DD}$	Supply Voltage	7	V
$T_{SC(O)}$	Output Short-circuit Duration, at $T_A=25^{\circ}\text{C}$ , $P_{TOT}=1\text{W}$	20	S
$T_A$	Operating Ambient Temperature range	-40 to 85	$^{\circ}\text{C}$
$T_J$	Maximum Junction Temperature	150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-65 to +150	$^{\circ}\text{C}$
$T_S$	Soldering Temperature , 10 seconds	260	$^{\circ}\text{C}$
$V_{ESD}$	Electrostatic Discharge	-3000 to 3000*1	V

Note : \*1. Human body model :  $C=100\text{pF}$  ,  $R=1500\Omega$  , 3 positive pulses plus 3 negative pulses

## Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{THJA}$	Thermal Resistance from Junction to Ambient in Free Air		
	DIP-8	109	K/W
	SO-8	210	K/W

## Electrical Characteristics

$V_{DD}=5\text{V}$  ,  $V_{SS}=0\text{V}$  ,  $T_A=25^{\circ}\text{C}$  ,  $f_i=1\text{kHz}$  ,  $R_L=32\Omega$  ( unless otherwise noted)

Symbol	Parameter	Test Condition	APA2308			Unit
			Min.	Typ.	Max	
<b>Supply</b>						
$V_{DD}$	Supply Voltage					V
	Single		3.0	5.0	6.0	
	Dual		$\pm 1.5$	$\pm 2.5$	$\pm 3.0$	
$V_{SS}$	Negative Supply Voltage		-1.5	-2.5	-3.0	V
$I_{DD}$	Supply Current	No Load		2.5	5	MA
$P_{TOT}$	Total Power Dissipation	No Load		12.5	25	mW

## Electrical Characteristics Cont.

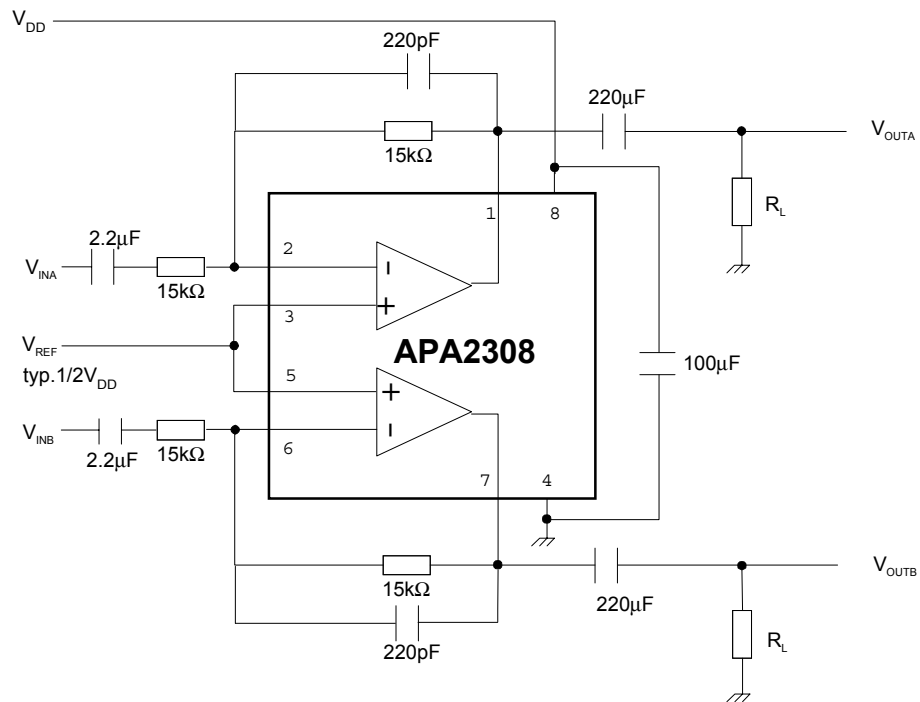
$V_{DD}=5V$ ,  $V_{SS}=0V$ ,  $T_A=25^{\circ}C$ ,  $f_i=1kHz$ ,  $R_L=32\Omega$  ( unless otherwise noted)

Symbol	Parameter	Test Condition	APA2308			Unit
			Min.	Typ.	Max	
<b>DC Characteristics</b>						
$V_{I(OS)}$	Input Offset Voltage			5		MV
$I_{BIAS}$	Input Bias Current			10		PA
$V_{CM}$	Common Mode Voltage		0		3.5	V
$G_V$	Open-loop Voltage Gain	$R_L=5k\Omega$		75		dB
$I_O$	Max. Output Current	$(THD+N)/S < 0.1\%$		140		MA
$R_O$	Output Resistance			0.25		$\Omega$
<b>AC Characteristics</b>						
$V_O$	Output Voltage Swing	$R_L=32\Omega^{*1}$	0.25		4.75	V
		$R_L=16\Omega^{*1}$	0.5		4.5	
PSRR	Power Supply Rejection Ratio	$F_i=100Hz$ $V_{RIPPLE(P-P)}=100mV$		65		dB
$\alpha_{CS}$	Channel Separation	$R_L=32\Omega$		95		dB
$C_L$	Load Capacitance				200	pF
(THD+N)/S	Total Harmonic Distortion Plus Noise to Signal Ratio	$R_L=32\Omega^{*2}$		-65	-60	dB
				0.05	0.1	%
S/N	Signal to Noise Ratio		90	100		dB
$F_G$	Unity Gain Frequency	$R_L=5k\Omega$		5		MHz
$P_O$	Max. Output Power	$(THD+N)/S < 0.1\%$		84		mW
$C_I$	Input Capacitance			3		pF
B	Power Bandwidth	Unity Gain Inverting		20		kHz

Notes \*1 : Values are proportional to  $V_{DD}$  ;  $(THD+N)/S < 0.1\%$

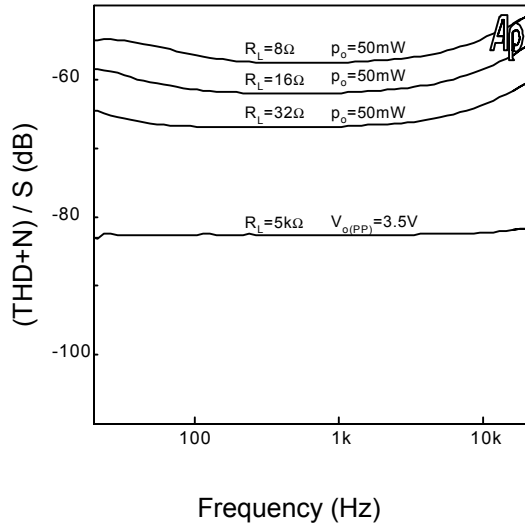
\*2 :  $V_{DD}=5.0V$  ;  $V_{O(P-P)}=3.5V$  (at 0 dB)

## Test And Application Circuits

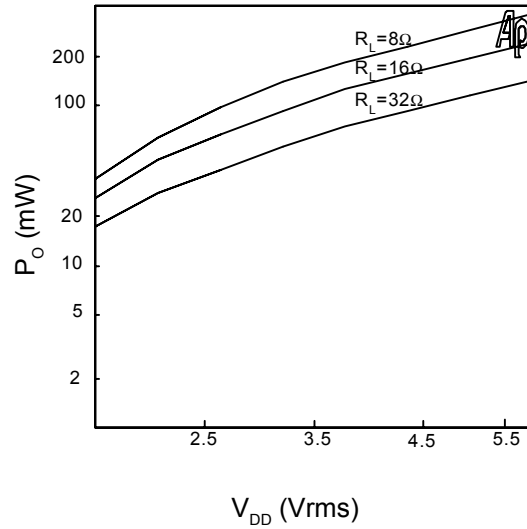


## Typical Characteristics

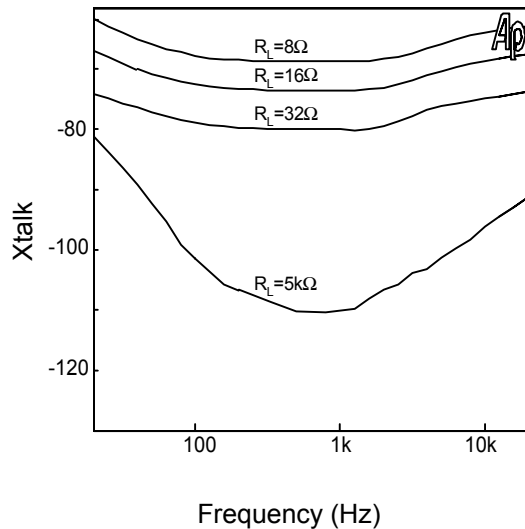
Total Harmonic Distortion Plus Noise-to-Signal Ratio as a Function of Input Frequency



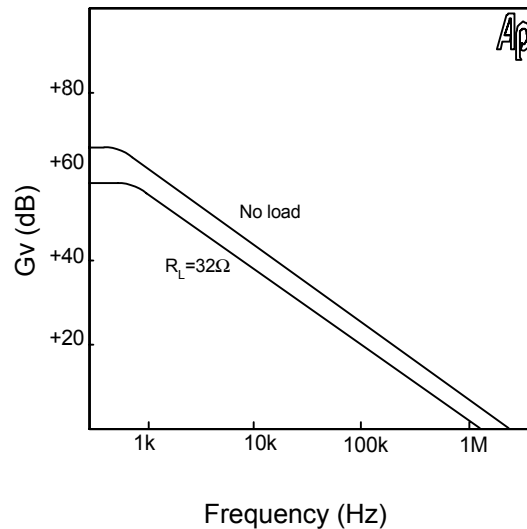
Output Power as a Function of Supply Voltage



Crosstalk as a Function of Input Frequency

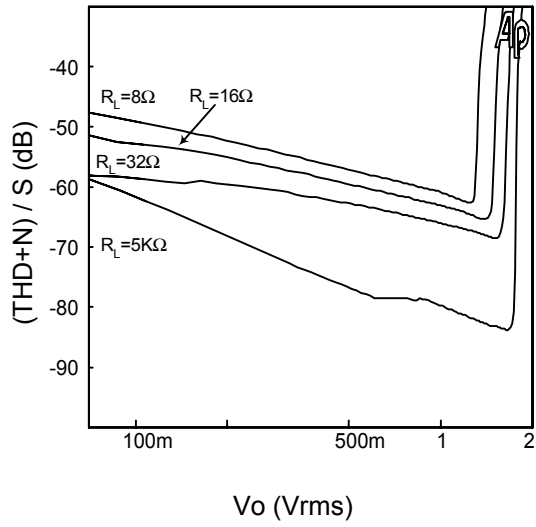


Open Loop Gain as a Function of Input Frequency



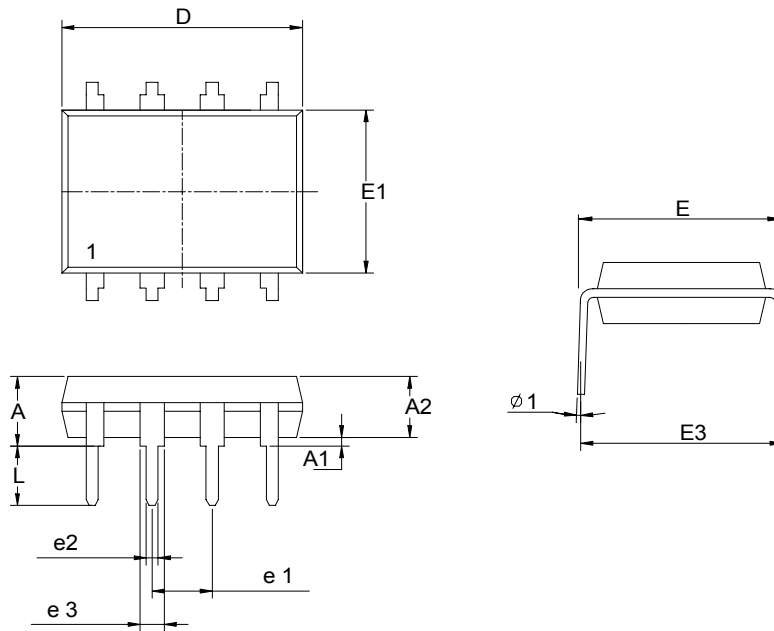
### Typical Characteristics Cont.

Total Harmonic Distortion Plus Noise-to-Signal Ratio as a Function of output Voltage



## Packaging Information

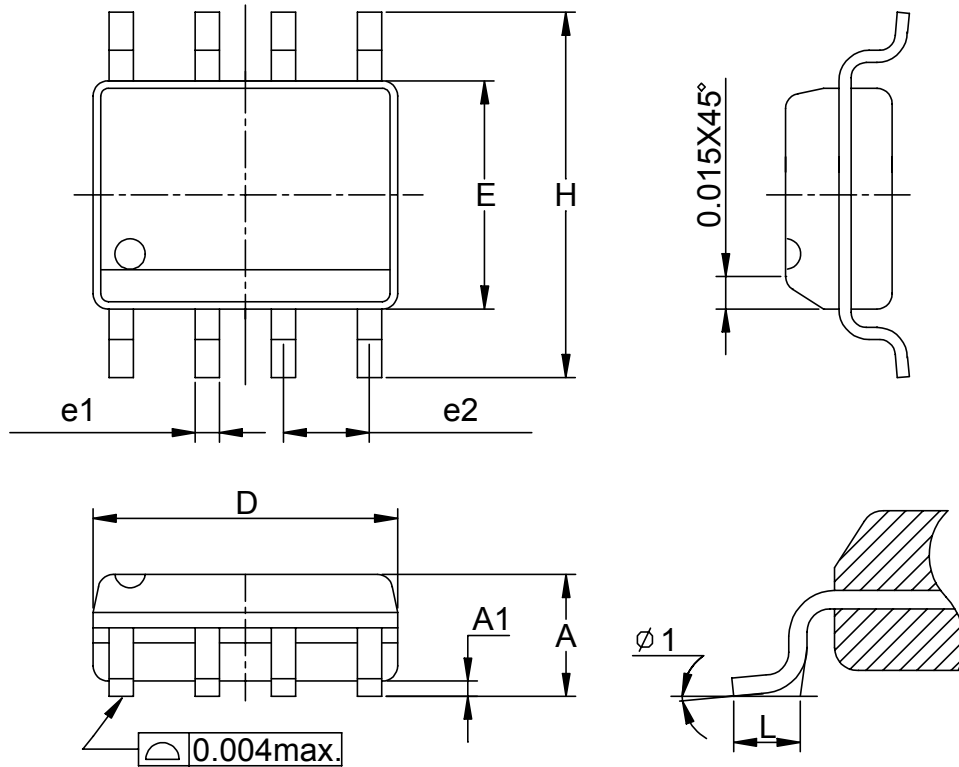
PDIP-8 pin ( Reference JEDEC Registration MS-001)



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		5.33		0.210
A1	0.38		0.015	
A2	2.92	3.68	0.115	0.145
D	9.02	10.16	0.355	0.400
e1	2.54BSC		0.100BSC	
e2	0.36	0.56	0.014	0.022
e3	1.14	1.78	0.045	0.070
E	7.62 BSC		0.300 BSC	
E1	6.10	7.11	0.240	0.280
E3		10.92		0.430
L	2.92	3.81	0.115	0.150
φ 1	15°		15°	

## Packaging Information

SOP-8 pin ( Reference JEDEC Registration MS-012)

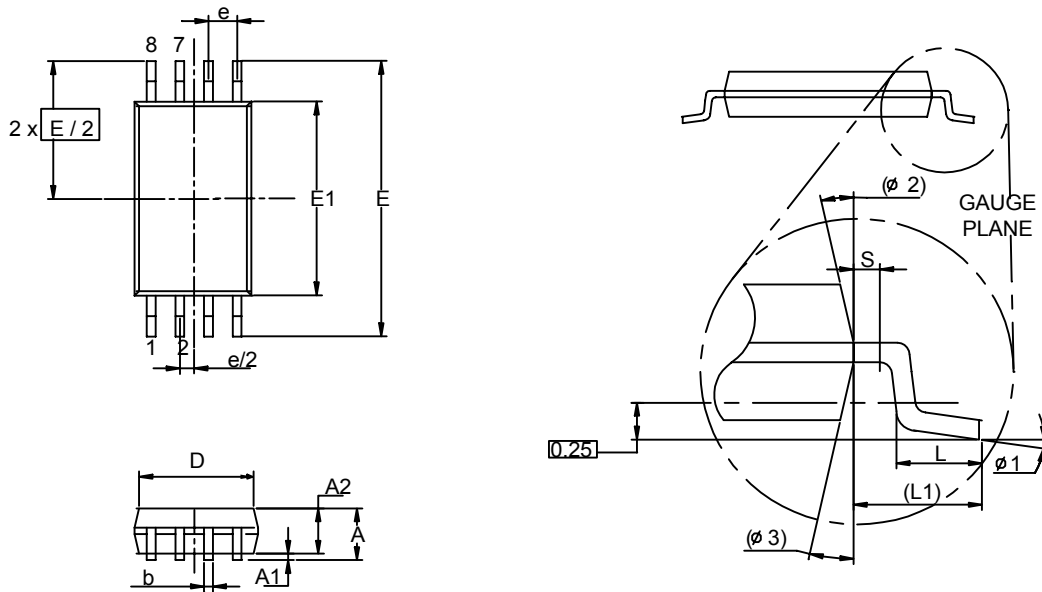


Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
H	5.80	6.20	0.228	0.244
L	0.40	1.27	0.016	0.050
e1	0.33	0.51	0.013	0.020
e2	1.27BSC		0.50BSC	
φ 1	8°		8°	



## Packaging Information

TSSOP-8



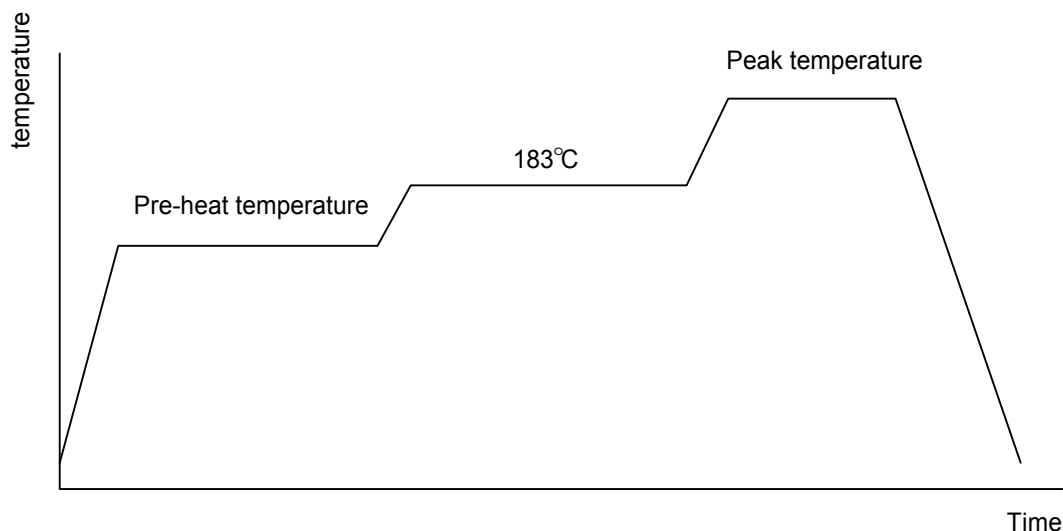
Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		1.2		0.047
A1	0.00	0.15	0.000	0.006
A2	0.80	1.05	0.031	0.041
b	0.19	0.30	0.007	0.012
D	2.9	3.1	0.114	0.122
e	0.65 BSC		0.026 BSC	
E	6.40 BSC		0.252 BSC	
E1	4.30	4.50	0.169	0.177
L	0.45	0.75	0.018	0.030
L1	1.0 REF		0.039 REF	
R	0.09		0.004	
R1	0.09		0.004	
S	0.2		0.008	
phi 1	0°	8°	0°	8°
phi 2	12° REF		12° REF	
phi 3	12° REF		12° REF	

## Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material : 90/10 or 63/37 SnPb)
Lead Solderability	Meets EIA Specification RSI86-91, ANSI/J-STD-002 Category 3.

## Reflow Condition (IR/Convection or VPR Reflow)

Reference JEDEC Standard J-STD-020A APRIL 1999



## Classification Reflow Profiles

	Convection or IR/ Convection	VPR
Average ramp-up rate(183°C to Peak)	3°C/second max.	10 °C /second max.
Preheat temperature 125 ± 25°C)	120 seconds max	
Temperature maintained above 183°C	60 – 150 seconds	
Time within 5°C of actual peak temperature	10 –20 seconds	60 seconds
Peak temperature range	220 +5/-0°C or 235 +5/-0°C	215-219°C or 235 +5/-0°C
Ramp-down rate	6 °C /second max.	10 °C /second max.
Time 25°C to peak temperature	6 minutes max.	

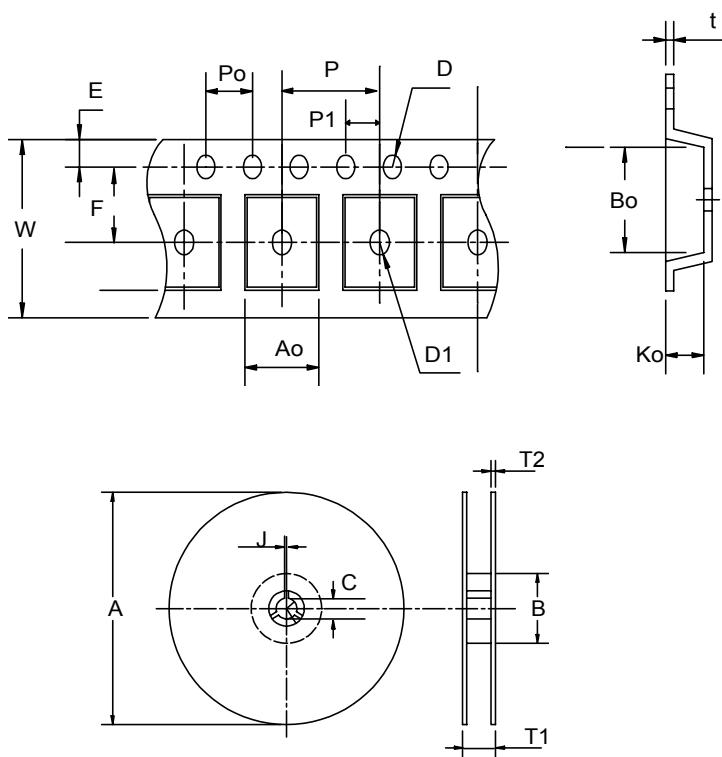
## Package Reflow Conditions

pkg. thickness ≥ 2.5mm and all bgas	pkg. thickness < 2.5mm and pkg. volume ≥ 350 mm <sup>3</sup>	pkg. thickness < 2.5mm and pkg. volume < 350mm <sup>3</sup>
Convection 220 +5/-0 °C		Convection 235 +5/-0 °C
VPR 215-219 °C		VPR 235 +5/-0 °C
IR/Convection 220 +5/-0 °C		IR/Convection 235 +5/-0 °C

## Reliability test Program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245° C , 5 SEC
HOLT	MIL-STD-883D-1005.7	1000 Hrs Bias @ 125 °C
PCT	JESD-22-B, A102	168 Hrs, 100 % RH , 121 °C
TST	MIL-STD-883D-1011.9	-65° C ~ 150° C , 200 Cycles
ESD	MIL-STD-883D-3015.7	VHBM > 2KV, VMM > 200V
Latch-Up	JESD 78	10ms , $I_{tr} > 100mA$

## Carrier Tape & Reel Dimensions



Application	A	B	C	J	T1	T2	W	P	E
SOP-8	330 ± 1	62 +1.5	12.75+ 0.15	2 ± 0.5	12.4 ± 0.2	2 ± 0.2	12± 0.3	8± 0.1	1.75±0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5± 1	1.55 +0.1	1.55+ 0.25	4.0 ± 0.1	2.0 ± 0.1	6.4 ± 0.1	5.2± 0.1	2.1± 0.1	0.3±0.013
Application	A	B	C	J	T1	T2	W	P	E
TSSOP-8	330 ± 1	62 +1.5	12.75+ 0.15	2 + 0.5	12.4 ± 0.2	2 ± 0.2	12± 0.3	8± 0.1	1.75±0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5 ± 0.1	1.5 + 0.1	1.5 + 0.1	4.0 ± 0.1	2.0 ± 0.1	7.0 ± 0.1	3.6 ± 0.3	1.6 ± 0.1	0.3±0.013

(mm)

## Cover Tape Dimensions

Application	Carrier Width	Cover Tape Width	Devices Per Reel
SOP- 8	12	9.3	2500
TSSOP- 8	12	9.3	2500

## Customer Service

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